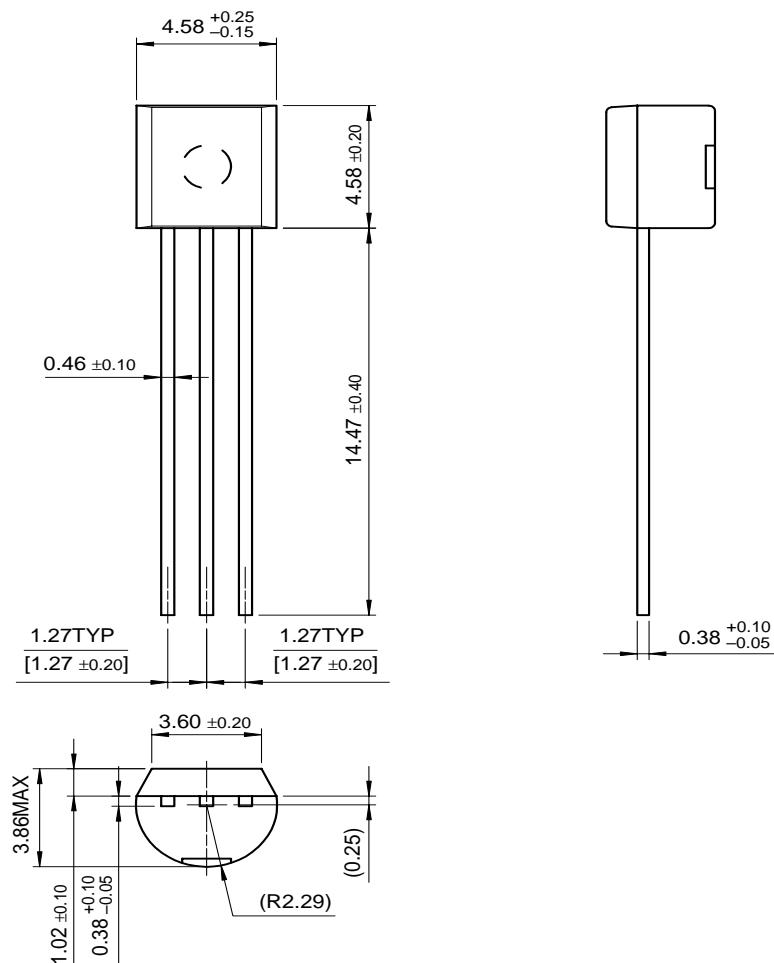


**Thermal Characteristics**  $T_A=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Max.	Units
$P_D$	Total Device Dissipation Derate above $25^\circ\text{C}$	625 5.0	mW mW/ $^\circ\text{C}$
$R_{\theta\text{JC}}$	Thermal Resistance, Junction to Case	83.3	$^\circ\text{C}/\text{W}$
$R_{\theta\text{JA}}$	Thermal Resistance, Junction to Ambient	200	$^\circ\text{C}/\text{W}$

## Package Dimensions

TO-92



Dimensions in Millimeters

## TRADEMARKS

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ACE <sup>TM</sup>	FACT <sup>TM</sup>	ImpliedDisconnect <sup>TM</sup>	PACMAN <sup>TM</sup>	SPM <sup>TM</sup>
ActiveArray <sup>TM</sup>	FACT Quiet Series <sup>TM</sup>	ISOPLANAR <sup>TM</sup>	POP <sup>TM</sup>	Stealth <sup>TM</sup>
Bottomless <sup>TM</sup>	FAST <sup>®</sup>	LittleFET <sup>TM</sup>	Power247 <sup>TM</sup>	SuperSOT <sup>TM-3</sup>
CoolFET <sup>TM</sup>	FAST <sup>TM</sup>	MicroFET <sup>TM</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>TM-6</sup>
CROSSVOLT <sup>TM</sup>	FRFET <sup>TM</sup>	MicroPak <sup>TM</sup>	QFET <sup>TM</sup>	SuperSOT <sup>TM-8</sup>
DOME <sup>TM</sup>	GlobalOptoisolator <sup>TM</sup>	MICROWIRE <sup>TM</sup>	QS <sup>TM</sup>	SyncFET <sup>TM</sup>
EcoSPARK <sup>TM</sup>	GTO <sup>TM</sup>	MSX <sup>TM</sup>	QT Optoelectronics <sup>TM</sup>	TinyLogic <sup>TM</sup>
E <sup>2</sup> CMOS <sup>TM</sup>	HiSeC <sup>TM</sup>	MSXPro <sup>TM</sup>	Quiet Series <sup>TM</sup>	TruTranslation <sup>TM</sup>
EnSigna <sup>TM</sup>	I <sup>2</sup> C <sup>TM</sup>	OCX <sup>TM</sup>	RapidConfigure <sup>TM</sup>	UHC <sup>TM</sup>
Across the board. Around the world. <sup>TM</sup> The Power Franchise <sup>TM</sup>		OCXPro <sup>TM</sup>	RapidConnect <sup>TM</sup>	UltraFET <sup>®</sup>
		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER <sup>®</sup>	VCX <sup>TM</sup>
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As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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